

آریا مدار ارجمند

SERIAL	ITEM	TECHNICAL DATA
1	Board Type	Rigid Board, RF
2	Material	FR4 Standard TG 140 °C, ROGERS, TEFLON
3	Layers	1-8 Layers Pcb Prototype (Don't Support Blind/Buried Vias)
4	Max Board Size	400mm * 500mm
5	Board Thickness	0.50mm - 3.20mm
6	Min line Width	0.15 mm
7	Min Space Width	0.15 mm
8	Min Hole Size	0.30 mm
9	Min Annular Ring	0.15mm
10	Copper Thickness	35um - 70um
11	Inner Layer Copper Thickness	18um ,35um
12	Solder Mask Color	Green, Black, White, Blue, Red, Yellow
13	Silkscreen (Legend) Color	White, Black, Yellow
14	Surface Finishing	HASL - Hot Air Solder Leveling ENIG - Electro less Nickel / Immersion Gold
15	Electrical Test	Yes
16	AOI (Automatic Optical Inspection) Test	Yes
17	Min Core Thickness For Multilayer	0.25 mm
18	FR4 TG 140 °C Prepreg Specification For Multi layer	106 RC 71.5% 57um 1080 RC 62% 76um 2113 RC 56% 100um 2116 RC 53% 130um 7628 RC 43% 200um